

Metal Plating Apparatus and Process

Abstract of the Disclosure

In order to make plating thickness uniform in a metal plating apparatus, a metal plating apparatus capable of performing metal plating to a uniform thickness is provided by aligning lines of electric force uniformly and in parallel by disposing a pair of conductive perforated plates 20a and 20b, which are electrically connected to each other, between plating metals 16 immersed in a plating solution and an object 18 to be plated.

FIG. 1 is a schematic diagram of a metal plating apparatus according to the present disclosure. The apparatus includes a plating tank 10 containing a plating solution. A pair of conductive perforated plates 20a and 20b are disposed in the tank, electrically connected to each other. Plating metals 16 and an object 18 to be plated are immersed in the solution between the plates.

Figures

Figure 1: A diagram illustrating the relationship between the variables x and y . The horizontal axis is labeled x and the vertical axis is labeled y . A curve is plotted in the first quadrant, starting from the origin and increasing as x increases. The curve is labeled $y = f(x)$. The area under the curve is shaded and labeled $\int_0^x f(t) dt$. The curve itself is labeled $f(x)$.